



## Material Content Data Sheet



<b>Sales Product Name</b>				SAK-TC234LA-32F200F AB		<b>Issued</b>		20. July 2018	
<b>MA#</b>				MA001503286					
<b>Package</b>				PG-TQFP-144-27		<b>Weight*</b>		702.92 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	39.071	5.56	5.56	55584	55584	
leadframe	inorganic material	phosphorus	7723-14-0	0.066	0.01		94		
	non noble metal	zinc	7440-66-6	0.265	0.04		377		
	non noble metal	iron	7439-89-6	5.302	0.75		7543		
wire	non noble metal	copper	7440-50-8	215.278	30.63	31.43	306264	314278	
	noble metal	gold	7440-57-5	0.002	0.00		3		
	noble metal	palladium	7440-05-3	0.049	0.01		69		
encapsulation	non noble metal	copper	7440-50-8	2.161	0.31	0.32	3074	3146	
	organic material	carbon black	1333-86-4	1.284	0.18		1827		
	plastics	epoxy resin	-	54.377	7.74		77359		
leadfinish	inorganic material	silicondioxide	60676-86-0	372.502	52.99	60.91	529934	609122	
	noble metal	palladium	7440-05-3	0.003	0.00		4		
	noble metal	silver	7440-22-4	0.003	0.00		4		
plating	noble metal	gold	7440-57-5	0.005	0.00		7		
	non noble metal	nickel	7440-02-0	4.713	0.67	0.67	6706	6721	
	noble metal	palladium	7440-05-3	0.000	0.00		1		
glue	non noble metal	nickel	7440-02-0	0.366	0.05		520		
	noble metal	silver	7440-22-4	0.000	0.00		1		
	noble metal	gold	7440-57-5	0.000	0.00	0.05	1	521	
*deviation	plastics	epoxy resin	-	1.644	0.23		2338		
	noble metal	silver	7440-22-4	5.827	0.83	1.06	8290	10628	
						Sum in total:	100.00	1000000	

### Important Remarks:

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